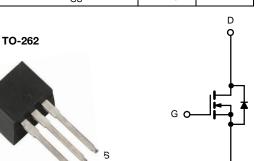


F1324L TO262-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ)			
30	0.0023 at V _{GS} = 10 V	150	82 nC			
30	0.0032 at V _{GS} = 4.5 V	120	02 110			



Top View

FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU



APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		150		
Continuous Drain Current (T. – 175 °C)	T _C = 70 °C		120	A	
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	35.8 ^{b, c}		
	T _A = 70 °C		27 ^{b, c}	^	
Pulsed Drain Current		I _{DM}	500		
Avalanche Current Pulse	1 0.4 ml 1	I _{AS}	39		
Single Pulse Avalanche Energy L = 0.1 mH		E _{AS}	94.8	mJ	
Continuous Course Prais Diade Current	T _C = 25 °C	1	90 ^{a, e}		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	A	
	T _C = 25 °C		250 ^a	w	
Manifestor Brown Binding the	T _C = 70 °C	В	175		
Maximum Power Dissipation	T _A = 25 °C	P _D	3.75 ^{b, c}		
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature R	T _J , T _{stg}	- 55 to 175	°C		

N-Channel MOSFET

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Тур.	Max.	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 sec	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	3C/VV		

Notes:

- a. Based on T_C = 25 °C.
 b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 sec. d. Maximum under steady state conditions is 90 °C/W.

服务热线:400-655-8788

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		35		\//90	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Wallana Basin Oamani		V _{DS} = 30 V, V _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α	
	В	$V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$		0.0023			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 37 \text{ A}$		0.0032		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 38.8 \text{ A}$		160		S	
Dynamic ^b							
Input Capacitance	C _{iss}			6201		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1725			
Reverse Transfer Capacitance	C _{rss}			970			
Total Cata Charma	Q_g $V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 38.8 \text{ A}$		171	257		
Total Gate Charge			81.5	123	-0		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 28.8 \text{ A}$		34		nC	
Gate-Drain Charge	Q _{gd}			29			
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_{L} = 0.625 \Omega$		11	17		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 24$ A, V_{GEN} = 10 V, R_g = 1 Ω		70	105		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 0.67 Ω		180	270	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 22.5 A, V_{GEN} = 4.5 V, R_g = 1 Ω		55	83		
Fall Time	t _f			12	18		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			120	Λ	
Pulse Diode Forward Current ^a	I _{SM}				120	A	
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 00 A di/d+ 100 A/ T 05 00		70.2	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		27			
Reverse Recovery Rise Time	t _b			25		ns	

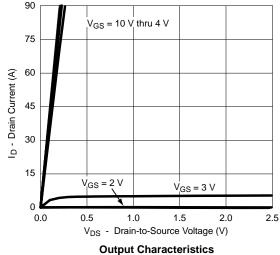
Notes:

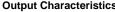
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

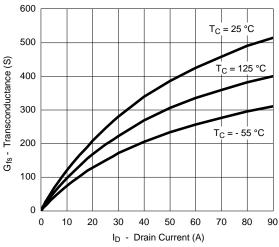
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



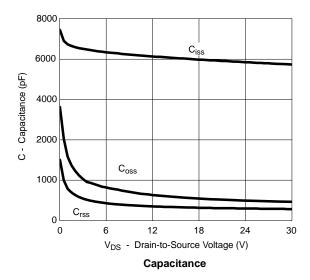
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





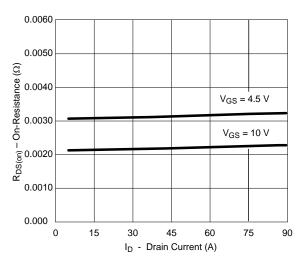


Transconductance

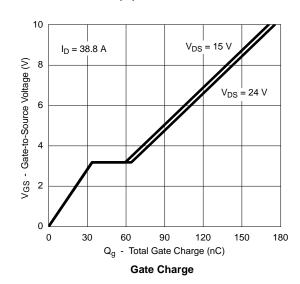


3.0 2.4 I_D - Drain Current (A) 1.8 1.2 T_C = 25 °C 0.6 T_C = 125 °C Γ_C = - 55 °C 0.0 V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics

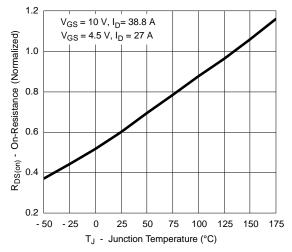


R_{DS(on)} vs. Drain Current

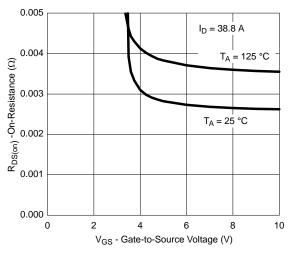




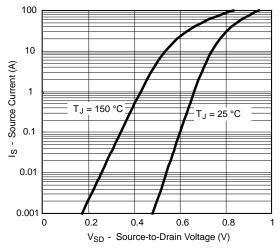
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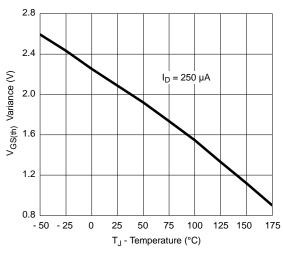
On-Resistance vs. Junction Temperature



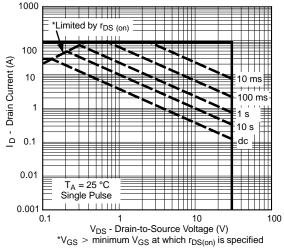
 $\rm R_{\rm DS(on)}$ vs. $\rm V_{\rm GS}$ vs. Temperature



Forward Diode Voltage vs. Temperature



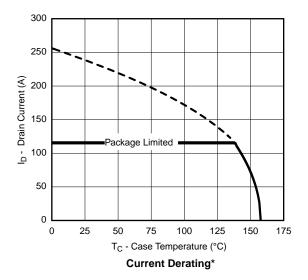
Threshold Voltage

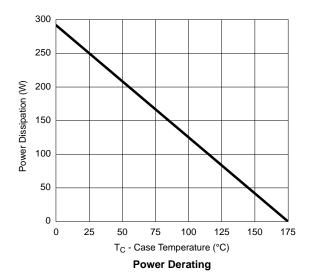


Safe Operating Area, Junction-to-Ambient

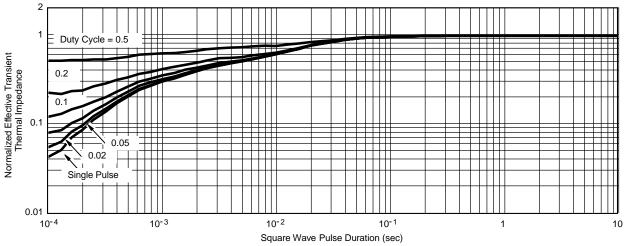


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





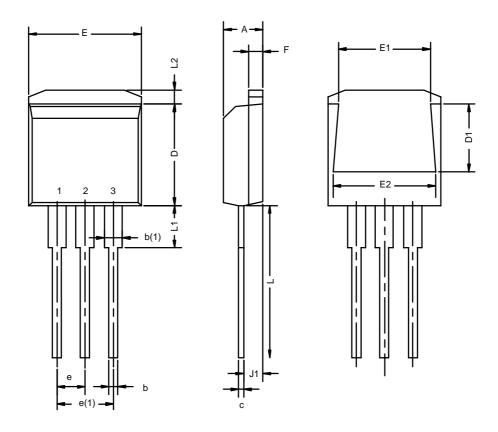
*The power dissipation P_D is based on $T_{J(max)}$ = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-262: 3-LEAD



	MILLIM	ETERS*	INC	HES	
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

^{*}Use millimeters as the primary measurement



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